

# **IRFR320B / IRFU320B**

## **400V N-Channel MOSFET**

#### **General Description**

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology.

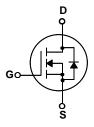
This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supplies and electronic lamp ballasts based on half bridge.

#### **Features**

- 3.1A, 400V,  $R_{DS(on)}$  = 1.75 $\Omega$  @V<sub>GS</sub> = 10 V Low gate charge ( typical 14 nC)
- Low Crss (typical 11 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability







# Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		IRFR320B / IRFU320B	Units
V <sub>DSS</sub>	Drain-Source Voltage		400	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°	°C)	3.1	Α
	- Continuous (T <sub>C</sub> = 100	O°C)	2.0	А
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	12.4	Α
$V_{GSS}$	Gate-Source Voltage		± 30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	240	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	3.1	Α
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	4.1	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.0	V/ns
P <sub>D</sub>	Power Dissipation (T <sub>A</sub> = 25°C) *		2.5	W
	Power Dissipation (T <sub>C</sub> = 25°C)		41	W
	- Derate above 25°C		0.33	W/°C
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Temperature Range		-55 to +150	°C
TL	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

#### **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		3.05	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		50	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		110	°C/W

<sup>\*</sup> When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions		Min	Тур	Max	Units
Off Cha	aracteristics						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		400			V
$\Delta BV_{DSS}$ / $\Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced	to 25°C		0.4		V/°C
I <sub>DSS</sub>	7 0 1 1/1 5 1 0 1	V <sub>DS</sub> = 400 V, V <sub>GS</sub> = 0 V				10	μΑ
	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 320 V, T <sub>C</sub> = 125°C				100	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V				100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
On Cha	racteristics						
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		2.0		4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1.55 A			1.4	1.75	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 1.55 A	(Note 4)		2.7		S
C <sub>iss</sub>	ic Characteristics Input Capacitance Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz			460 55	600 72	pF pF
C <sub>oss</sub>	Output Capacitance				55	72	pF
C <sub>rss</sub>	Reverse Transfer Capacitance				11	15	pF
Switchi	ing Characteristics						
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 200 V, I <sub>D</sub> = 3.3 A,			10	30	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 200 \text{ V}, I_D = 3.3 \text{ A},$ $R_G = 25 \Omega$			35	80	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	NG = 20 32			35	80	ns
t <sub>f</sub>	Turn-Off Fall Time		(Note 4, 5)		35	80	ns
Qg	Total Gate Charge	$V_{DS} = 320 \text{ V}, I_{D} = 3.3 \text{ A},$		-	14	18	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V			2.7		nC
Q <sub>gd</sub>	Gate-Drain Charge		(Note 4, 5)		5.6		nC
Drain-S	Source Diode Characteristics ar	nd Maximum Ratings	6				
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current					3.1	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current					12.4	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 3.1 \text{ A}$				1.5	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 3.3 \text{ A},$			220		ns
711							

- Notes: 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 43.7mH, I<sub>AS</sub> = 3.1A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25  $\Omega$ , Starting T<sub>J</sub> = 25°C 3. I<sub>SD</sub>  $\leq$  3.3A, di/dt  $\leq$  200A/µs, V<sub>DD</sub>  $\leq$  BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C 4. Pulse Test : Pulse width  $\leq$  300µs, Duty cycle  $\leq$  2% 5. Essentially independent of operating temperature

# **Typical Characteristics**

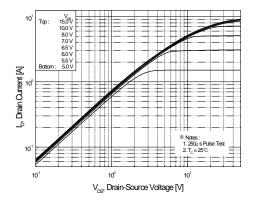


Figure 1. On-Region Characteristics

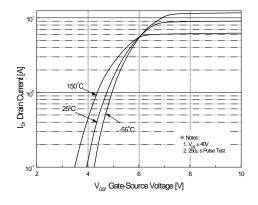


Figure 2. Transfer Characteristics

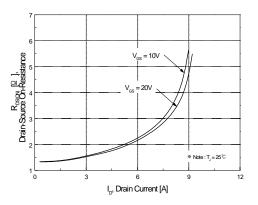


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

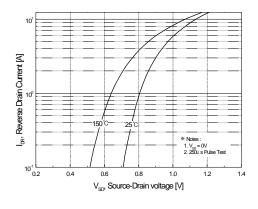


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

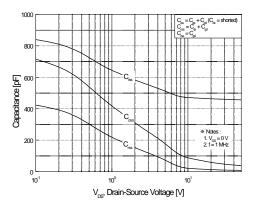


Figure 5. Capacitance Characteristics

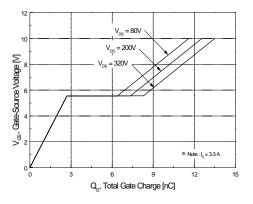


Figure 6. Gate Charge Characteristics

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# Typical Characteristics (Continued)

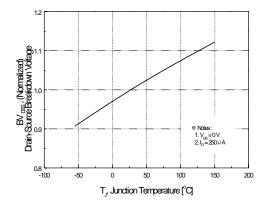


Figure 7. Breakdown Voltage Variation vs Temperature

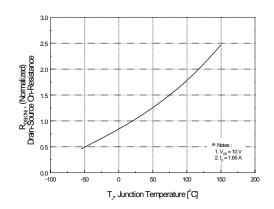


Figure 8. On-Resistance Variation vs Temperature

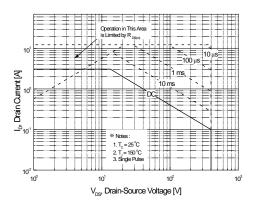


Figure 9. Maximum Safe Operating Area

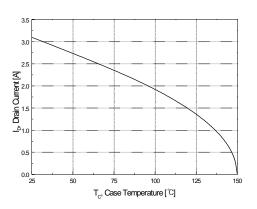


Figure 10. Maximum Drain Current vs Case Temperature

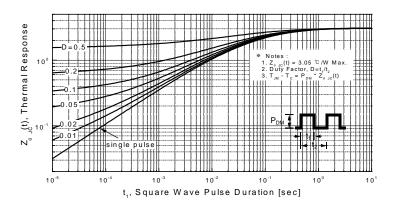
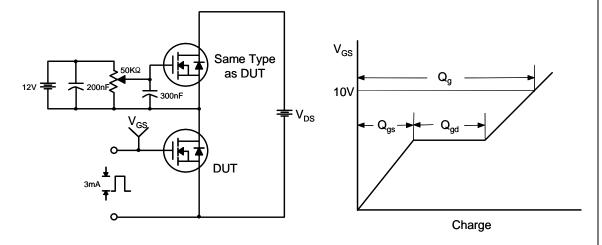


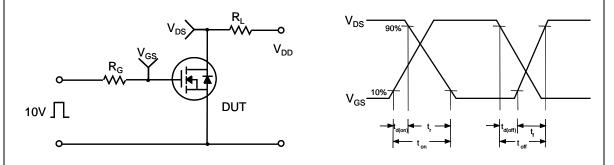
Figure 11. Transient Thermal Response Curve

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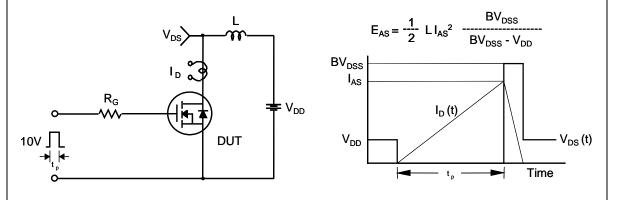
## **Gate Charge Test Circuit & Waveform**



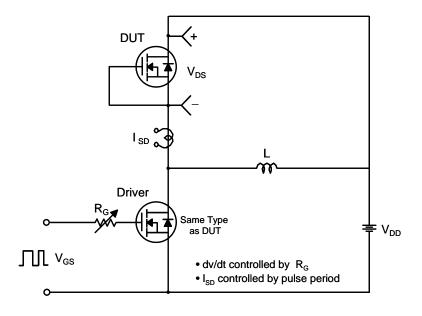
## **Resistive Switching Test Circuit & Waveforms**

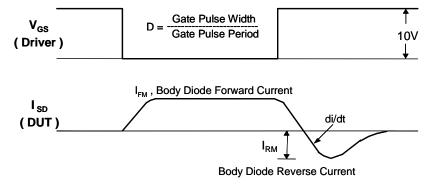


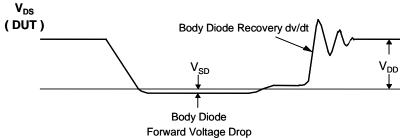
## **Unclamped Inductive Switching Test Circuit & Waveforms**



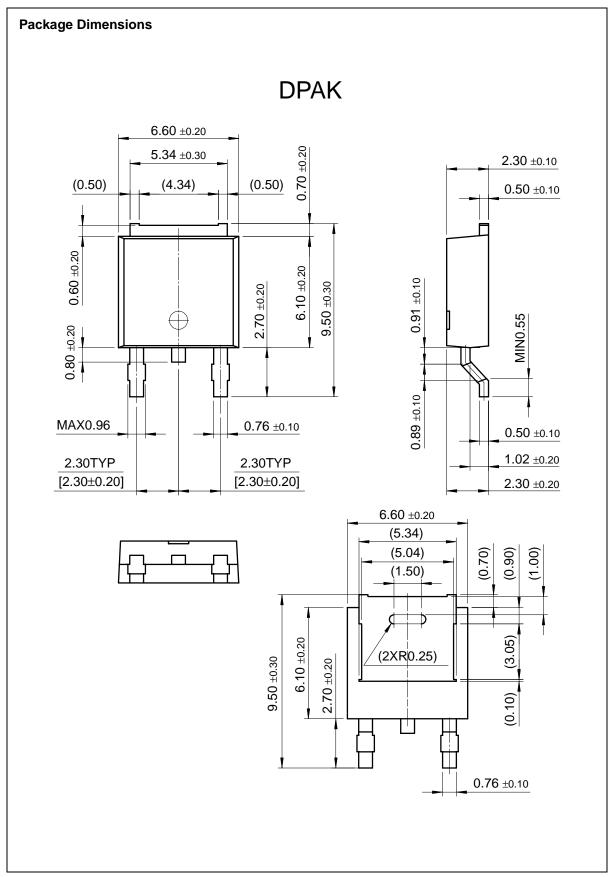
## Peak Diode Recovery dv/dt Test Circuit & Waveforms





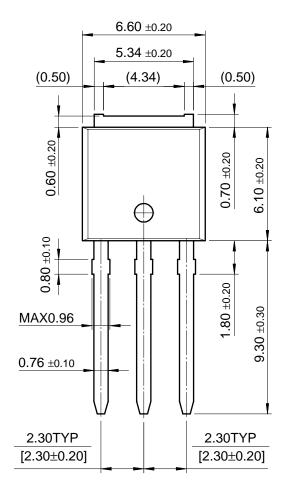


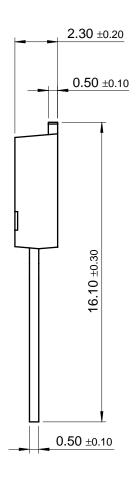
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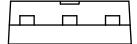




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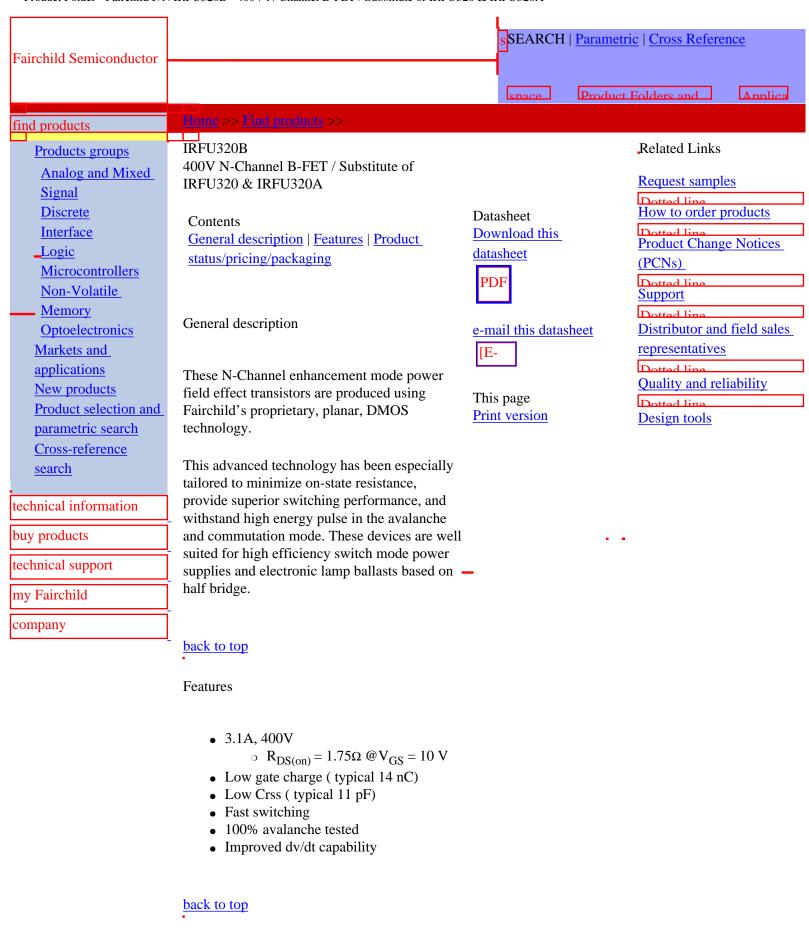
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Product status/pricing/packaging



Product Product status Pricing\* Package type Leads Packing method

Product Folder - Fairchild P/N IRFU320B - 400V N-Channel B-FET / Substitute of IRFU320 & IRFU320A

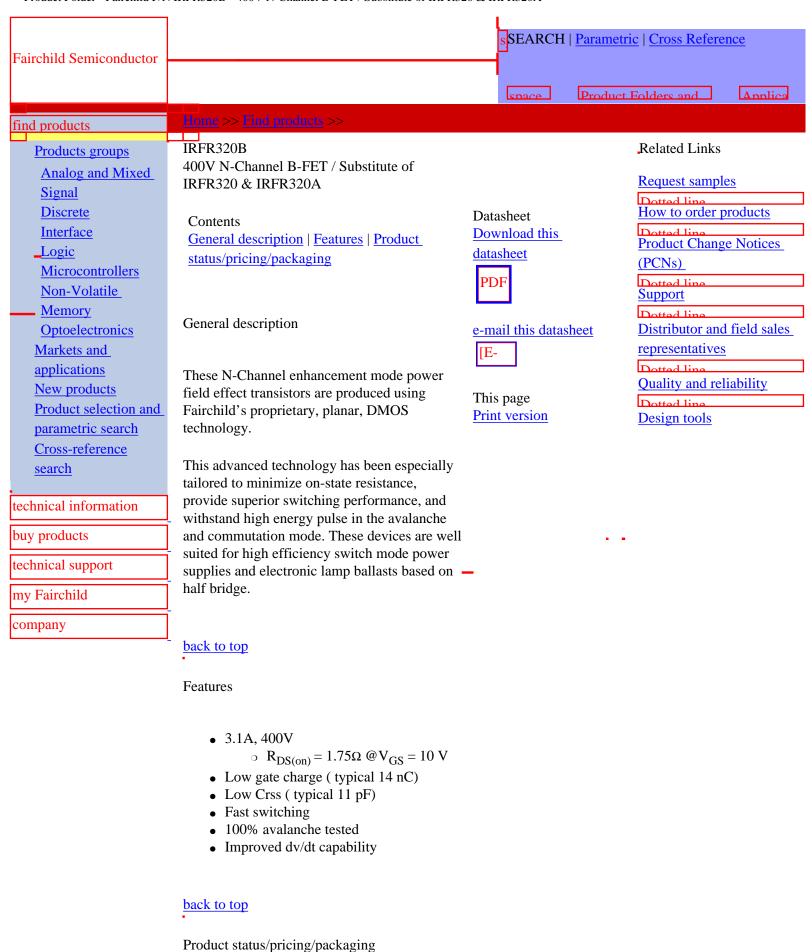
IRFU320BTU	Full Production	\$0.49	TO-251(IPAK)	3	RAIL

<sup>\* 1,000</sup> piece Budgetary Pricing

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Product Product status Pricing\* Package type Leads Packing method

IRFR320BTF	Full Production	\$0.49	TO-252(DPAK)	2	TAPE REEL
IRFR320BTM	Full Production	\$0.49	TO-252(DPAK)	2	TAPE REEL

<sup>\* 1,000</sup> piece Budgetary Pricing

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